

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Alcoe et al.

Art Unit:

Serial No.:

Dkt. No.: END920010135US2

Filed:

Examiner:

Title: **THERMALLY ENHANCED LID FOR MULTICHIP MODULES**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**Preliminary Amendment**

Sir:

Kindly enter this amendment prior to initial examination

**In the Specification:**

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No.  
10/198,393; filed on 7/16/2002.--